

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	6	(circuit adj board and substrate and (die chip) and (flexible with support)).clm.	US-PGPUB	OR	ON	2005/11/23 16:48
S1	1283	(heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible) same support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:04
S2	7283	(heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:33
S3	2905	"257"/\$.ccls. and (heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/28 15:15
S4	4284	substrate and (heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/28 15:15
S5	2194	"257"/\$.ccls. and substrate and (heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:11
S6	596	"438"/\$.ccls. and substrate and (heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/28 17:21
S7	122	(heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible) same support) and @pd>"20050527"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:04
S8	603	(heat adj (sink spreader (dissipation adj device))) and (die chip) and ((spring flexible)) and @pd>"20050527"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:34
S9	172	257/706,717,718,720,796,675.ccls. and @pd>"20050527"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:29

S10	12356	circuit adj board and substrate and (die chip) and flexible	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:30
S12	1167	circuit adj board and substrate and (die chip) and (flexible with support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:58
S13	1585	circuit adj board and substrate and (die chip) and (flexible with support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 16:48

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